

PAT-NO: JP404252049A
DOCUMENT-IDENTIFIER: JP 04252049 A
TITLE: WAFER MOUNTING METHOD
PUBN-DATE: September 8, 1992

INVENTOR-INFORMATION:

NAME

YASUTAKE, HIROYUKI

ASSIGNEE-INFORMATION:

NAME

NEC KYUSHU LTD

COUNTRY

N/A

APPL-NO: JP03001351

APPL-DATE: January 10, 1991

INT-CL (IPC): H01L021/78, H01L021/68

US-CL-CURRENT: 438/FOR.386

ABSTRACT:

PURPOSE: To automatically expand the interval between pellets after a dicing operation and to eliminate a need for a tape expansion process before a pellet mounting operation by a method wherein a two-stage tension difference is given to a dicing tape at a wafer-mounting part and at its outside part.

CONSTITUTION: A dicing tape 2 is expanded; a wafer 1 is mounted on its upper part. Then, the tape is stretched further, its expansion amount is increased and a frame 3 is mounted. After that, a dicing operation is performed by using a blade 4. As a result, the tension of the dicing tape at the outside part becomes stronger than that of the mounting part of the wafer. Consequently,

the interval between pellets is expanded automatically by the two-stage tension difference of the dicing tape after the dicing operation, and a process to expand the tape is not required before the pellets are mounted.

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